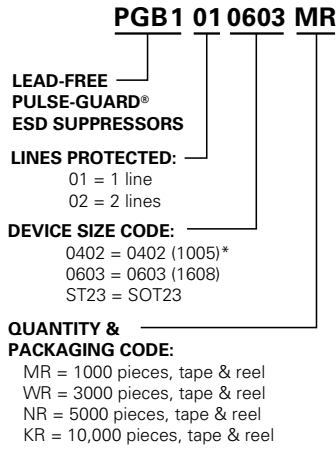
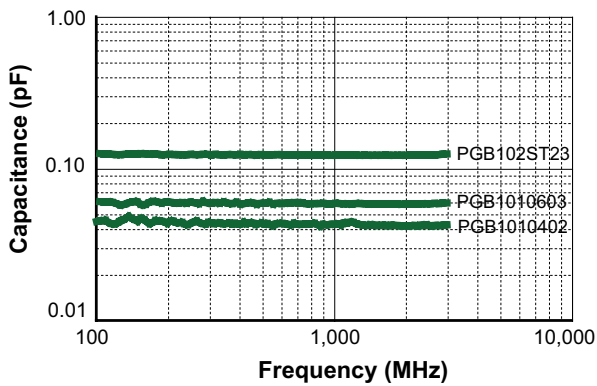


**Part Numbering System**

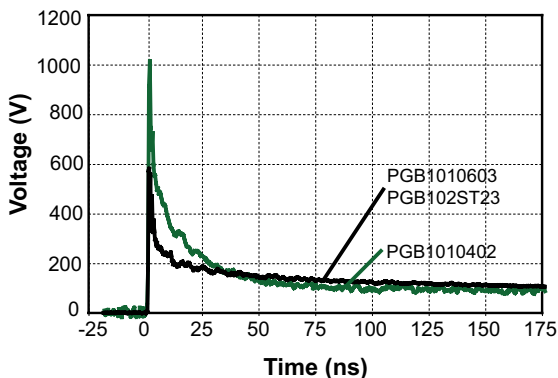


\*Note: PGB1 0402 product not available as Halogen Free item. See PGB2 0402 product instead, part number PGB2010402KRHF (<http://www.littelfuse.com/series/PGB2010402.html>).

**Typical Device Capacitance**

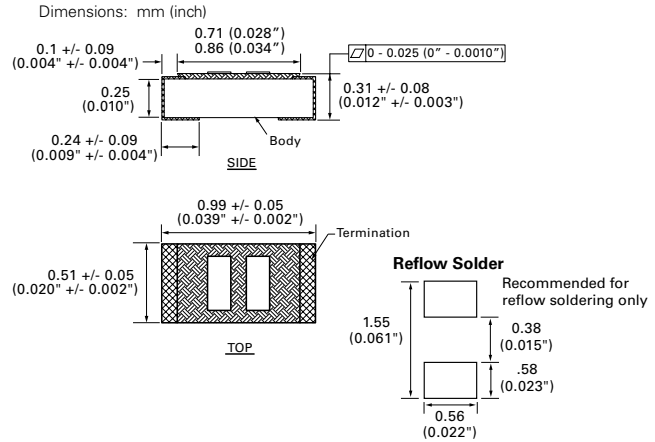


**Typical ESD Response**

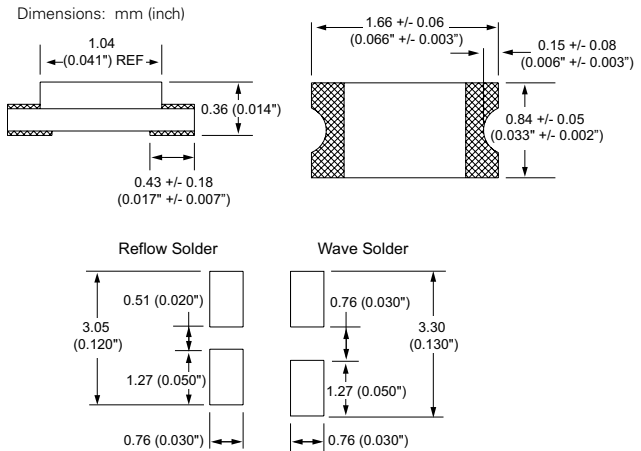


**Dimensions**

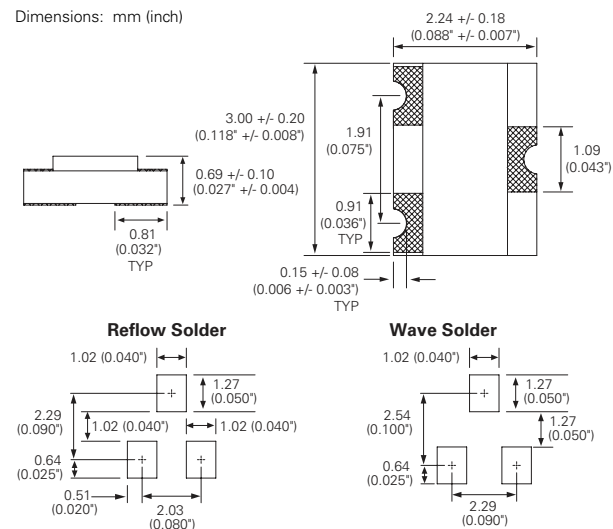
**0402 Device**



**0603 Device**



**SOT23 Device**



### Physical Specifications

<b>Materials</b>	Body: Glass Epoxy Terminations: Copper/Nickel/Tin
<b>Solderability</b>	MIL-STD-202, Method 208
<b>Soldering Parameters</b>	Wave solder - 260°C, 10 seconds maximum Reflow solder - 260°C, 30 seconds maximum

### Design Consideration

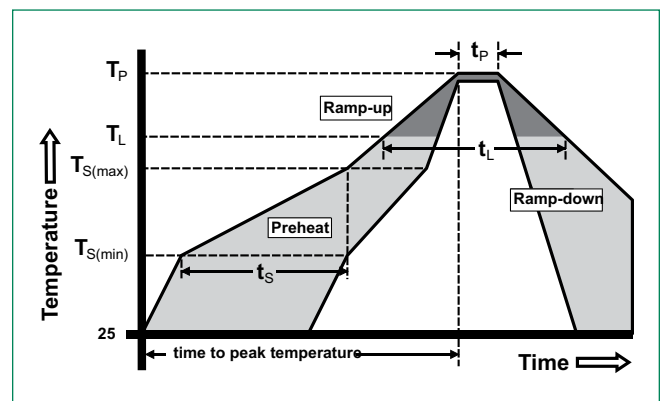
Because of the fast rise-time of the ESD transient, proper placement of PULSE-GUARD® suppressors are a key design consideration to achieving optimal ESD suppression. The devices should be placed on the circuit board as close to the source of the ESD transient as possible. Install PULSE-GUARD® suppressors (connected from signal/data line to ground) directly behind the connector so that they are the first board-level circuit component encountered by the ESD transient.

### Environmental Specifications

<b>Operating Temperature</b>	-65°C to +125°C
<b>Moisture Resistance</b>	0402 series: 40°C, 95% RH, 1000 hours 0603, ST23: 85°C, 85% RH, 1000 hours
<b>Thermal Shock</b>	MIL-STD-202, Method 107, -65°C to 125°C, 30 min. cycle, 10 cycles
<b>Vibration</b>	MIL-STD-202, Method 201, (10 to 55 to 10 Hz, 1 min. cycle, 2 hrs each in X-Y-Z)
<b>Chemical Resistance</b>	MIL-STD-202, Method 215
<b>Solder Leach Resistance and Terminal Adhesion</b>	IPC/EIA J-STD-002

### Soldering Parameters

<b>Reflow Condition</b>	Pb – Free assembly	
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 180 seconds
<b>Average ramp up rate (Liquidus Temp (<math>T_L</math>) to peak)</b>	3°C/second max	
<b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>	3°C/second max	
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_L$ )	60 – 150 seconds
<b>Peak Temperature (<math>T_p</math>)</b>	260°C	
<b>Time within 5°C of actual peak Temperature (<math>t_p</math>)</b>	10 – 30 seconds	
<b>Ramp-down Rate</b>	6°C/second max	
<b>Time 25°C to peak Temperature (<math>T_p</math>)</b>	8 minutes max	

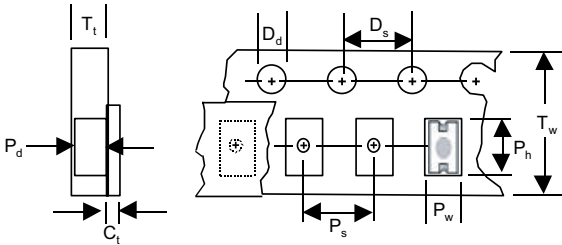


Based on IPC/JEDEC J-STD-020

**Packaging**

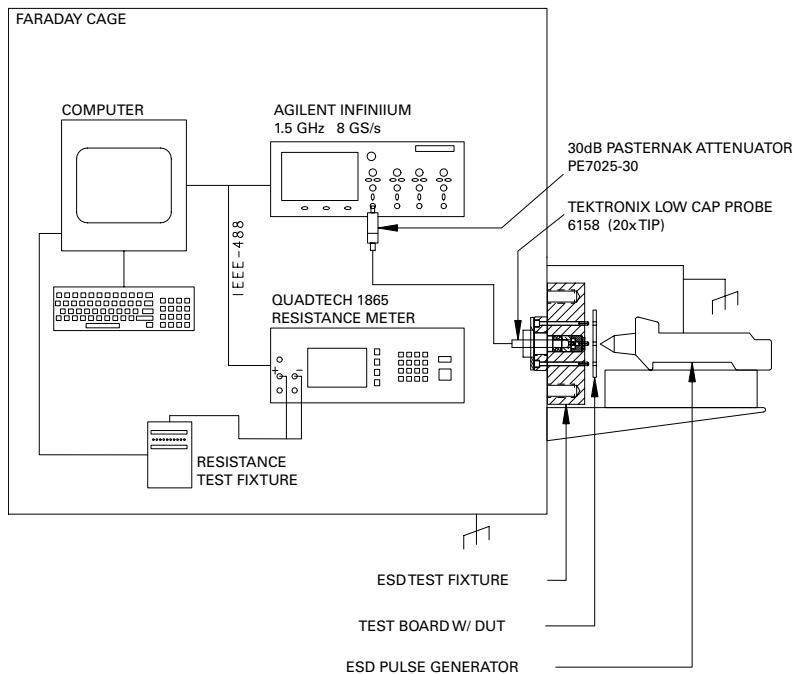
Part Number	Quantity & Packaging Code	Quantity	Packaging Option	Packaging Specification
PGB1010402	KR	10000	Tape & Reel (7" reel)	EIA RS-481-1 (IEC 286, part 3)
PGB1010603	MR	1000	Tape & Reel (7" reel)	EIA RS-481-1 (IEC 286, part 3)
PGB102ST23	WR	3000	Tape & Reel (7" reel)	EIA RS-481-1 (IEC 286, part 3)
PGB1010603	NR	5000	Tape & Reel (7" reel)	EIA RS-481-1 (IEC 286, part 3)

**Tape and Reel Specifications**



Description	0402 Series (mm)	0603 Series (mm)	SOT23 Series (mm)
C <sub>t</sub> - Cover tape thickness	0.05	0.05	0.06
D <sub>d</sub> - Drive hole diameter	1.50	1.50	1.50
D <sub>s</sub> - Drive hole spacing	4.00	4.00	4.00
P <sub>d</sub> - Pocket depth	0.41	0.58	1.02
P <sub>h</sub> - Pocket height	1.12	1.85	3.23
P <sub>s</sub> - Pocket spacing	2.00	4.00	4.00
P <sub>w</sub> - Pocket width	0.62	1.02	2.46
T <sub>t</sub> - Carrier tape thickness	0.61	0.65	1.77
T <sub>w</sub> - Carrier tape width	8.00	8.00	8.00

**Typical Test Setup**



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[PGB102ST23WRHF](#) [PGB1010603MR](#) [PGB1010603MRHF](#)